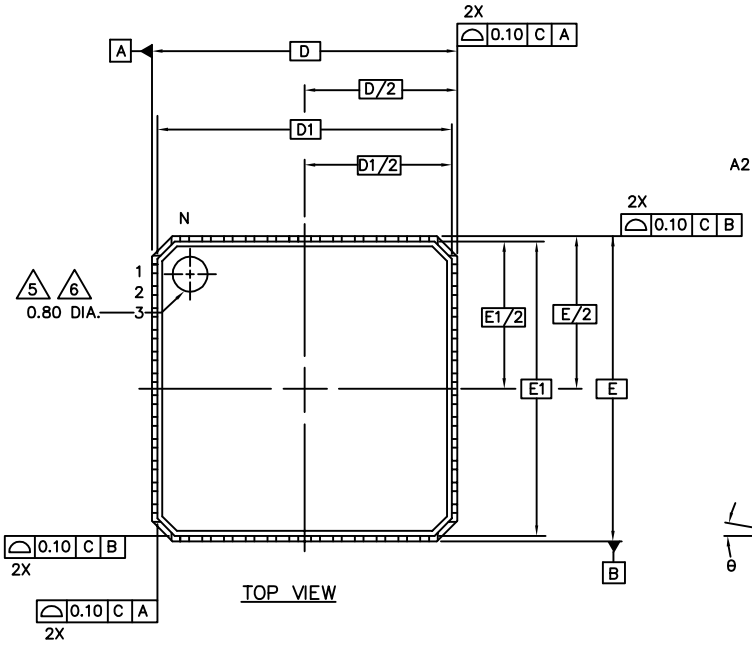
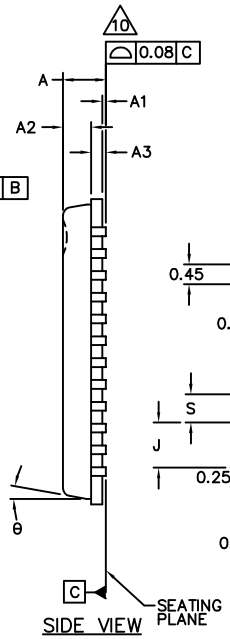
NOTES : ANY MOLD FLASH ON THE RING PAD AREA SHALL BE ALLOWABLE.

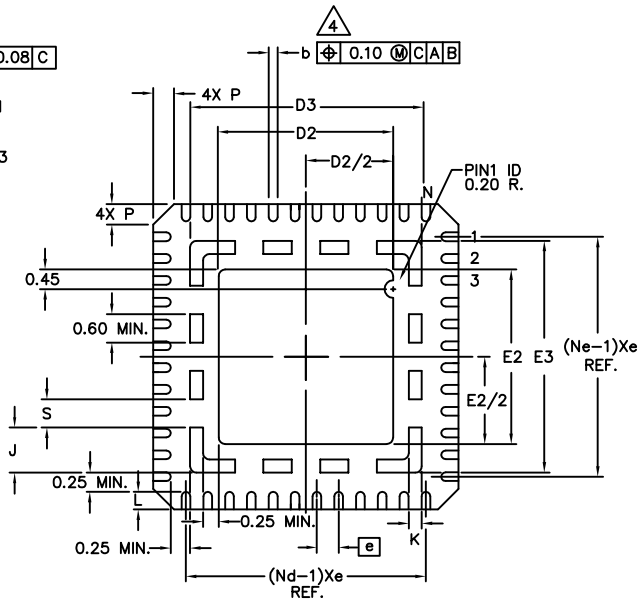
MIXED RING HIGH DENSITY LEADFRAME



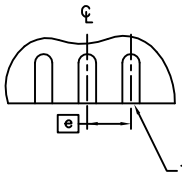
TOP VIEW



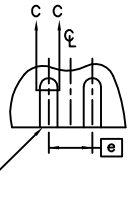
SIDE VIEW



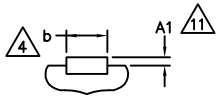
BOTTOM VIEW



FOR ODD TERMINAL/SIDE



FOR EVEN TERMINAL/SIDE



SECTION "C–C"
SCALE: NONE

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE, MLF2, 7 X 7 mm BODY

SIZE	DWG NUMBER	REV
A3	45277	08

SCALE: PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING

SHEET 3 OF 5